

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10055445	FILING DATE 01/23/2002	CLASS 438	SUBCLASS 462	GAU 2812	2829	EXAMINER Geyn
**APPLICANTS: Potts David;						
**CONTINUING DATA VERIFIED: THIS APPLN-CLAIMS BENEFIT OF 60/344,161 12/27/2001						
** FOREIGN APPLICATIONS VERIFIED:						
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>		
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no				ATTORNEY DOCKET NO		
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no				TI-27832		
Verified and Acknowledged Examiners's initials						
TITLE : Semiconductor wafer with grouped integrated circuit die having inter-die connections for group testing						
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)						

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	
		Print Claim for O.G.	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM

(Attached in pocket on right inside flap)